

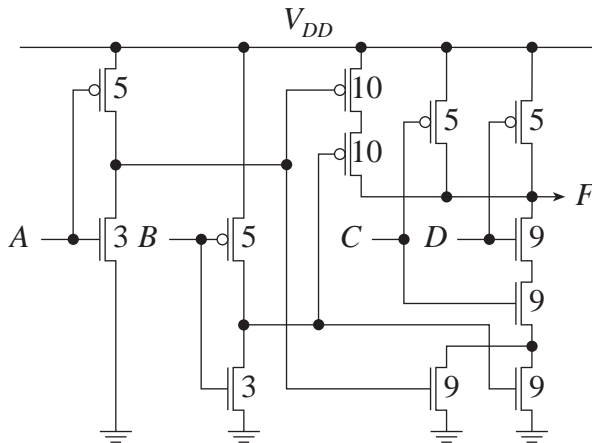
## Solutions to exam 2019-10-21 in TSTE86 Digital ICs

1.

a) Switch nets for function  $F$ :

$$F = AB + \overline{CD} = AB + \overline{C} + \overline{D} \Rightarrow \begin{cases} S_p = F(\overline{A}, \overline{B}, \overline{C}, \overline{D}) = \overline{A}\overline{B} + C + D \\ S_n = \overline{F(A, B, C, D)} = \overline{\overline{A}\overline{B} + C + D} = (\overline{A} + \overline{B})CD \end{cases}$$

Two inverters are needed for  $A'$  and  $B'$ . Transistor schematic:



b) Aspect ratios are indicated directly by the transistors in the schematic above

2.

From the data it can be seen that  $V_{DS} > V_{DSAT}$  for all sets  $\Rightarrow$  no operating mode is resistive. To decide between saturated and velocity saturated operating modes we need to compare  $V_{GT}$  and  $V_{DSAT} = 0.58$  V. Inspecting the data sets we see the smallest  $V_{GT} = 2 - V_T$ . Hence we obtain that the MOSFET is velocity saturated for all sets if  $2 - V_T < 0.58 \Rightarrow V_T \leq 1.42$  V, which seems likely, so let us guess that and verify it later.

$$I_D = \left( k' \frac{W}{L} V_{DSAT} \right) \left( V_{GS} - V_{T0} - \frac{V_{DSAT}}{2} \right) (1 + \lambda V_{DS}) = P_1 \cdot P_2 \cdot P_3$$

a) Find  $V_{T0}$  e.g. by comparing the relative currents of data set 1 and 2

$$\frac{I_{D1}}{I_{D2}} = \frac{P_1 \left( 2.5 - V_{T0} - \frac{0.58}{2} \right) P_3}{P_1 \left( 2.0 - V_{T0} - \frac{0.58}{2} \right) P_3} = \frac{1812}{1297} \Rightarrow V_{T0} \approx 0.45 \text{ V}$$

b)  $\gamma$  is easy to solve if we solve c) first

c) We can find  $2|\Phi_F|$  in the  $V_T$ -equation for data set 4 and 5, so we start by finding  $V_{T4}$  and  $V_{T5}$

Data set 2 is numerically close to 4 and 5, so we use that in calculations of  $V_{T4}$  and  $V_{T5}$

$$\frac{I_{D2}}{I_{D4}} \approx \frac{P_1 \left( 2 - 0.45 - \frac{0.58}{2} \right) P_3}{P_1 \left( 2 - V_{T4} - \frac{0.58}{2} \right) P_3} = \frac{1297}{1141} \Rightarrow V_{T4} \approx 0.60 \text{ V}$$

$$\frac{I_{D2}}{I_{D5}} \approx \frac{P_1 \left( 2 - 0.45 - \frac{0.58}{2} \right) P_3}{P_1 \left( 2 - V_{T5} - \frac{0.58}{2} \right) P_3} = \frac{1297}{1039} \Rightarrow V_{T5} \approx 0.70 \text{ V}$$

Now we use the relation  $V_T = V_{T0} + \gamma \left( \sqrt{|V_{SB} - 2\Phi_F|} - \sqrt{|2\Phi_F|} \right)$  to find  $2|\Phi_F|$

$$\text{Let } x = 2\Phi_F (< 0) \Rightarrow \frac{V_{T4} - V_{T0}}{V_{T5} - V_{T0}} = \frac{\sqrt{|1-x|} - \sqrt{|x|}}{\sqrt{|2-x|} - \sqrt{|x|}} = \frac{\sqrt{1-x} - \sqrt{-x}}{\sqrt{2-x} - \sqrt{-x}} \approx \frac{0.60 - 0.45}{0.70 - 0.45} \Rightarrow$$

$$x \approx -0.60 \text{ V} \Rightarrow 2|\Phi_F| \approx 0.60 \text{ V}$$

b) *continued*

Insert numerical values into e.g. set 4

$$V_{T4} = V_{T0} + \gamma \left( \sqrt{|V_{SB4} - 2\Phi_F|} - \sqrt{|2\Phi_F|} \right) \approx 0.45 + \gamma \left( \sqrt{|1 - (-0.60)|} - \sqrt{|-0.60|} \right) \approx 0.60$$

$$\Rightarrow \gamma \approx 0.30 \text{ V}^{1/2}$$

d) To find  $W/L$ , we e.g. start by finding  $\lambda$  from data set 2 and 3 that are numerically close

$$\frac{I_{D2}}{I_{D3}} = \frac{P_1 P_2 (1 + \lambda \cdot 1.8)}{P_1 P_2 (1 + \lambda \cdot 2.5)} = \frac{1297}{1361} \Rightarrow \lambda \approx 0.081 \text{ V}^{-1}$$

$W/L$  can now be found from any of data sets, e.g. set 2

$$I_{D2} \approx 122 \cdot 10^{-6} \cdot \frac{W}{L} \cdot 0.58 \cdot \left( 2 - 0.45 - \frac{0.58}{2} \right) (1 + 0.081 \cdot 1.8) \approx 1297 \cdot 10^{-6} \Rightarrow \frac{W}{L} \approx 13$$

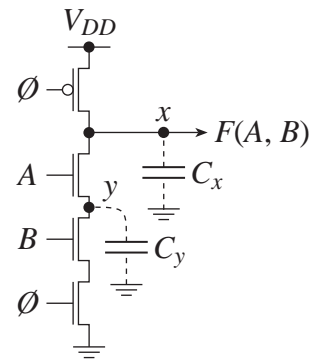
a), b), c), d): check assumption on threshold voltages

$$\left. \begin{aligned} V_{BS1} = V_{BS2} = V_{BS3} = 0 &\Rightarrow V_{T1} = V_{T2} = V_{T3} = V_{T0} \approx 0.45 \text{ V} \leq 1.42 \text{ V} \\ V_{T4} \approx 0.60 \text{ V} &\leq 1.42 \text{ V} \\ V_{T5} \approx 0.70 \text{ V} &\leq 1.42 \text{ V} \end{aligned} \right\} \Rightarrow \text{assumption is ok}$$

3.

a)  $F(A, B) = \overline{AB} \Rightarrow S_n = AB$ . The corresponding transistor schematic is shown in the figure to the right.

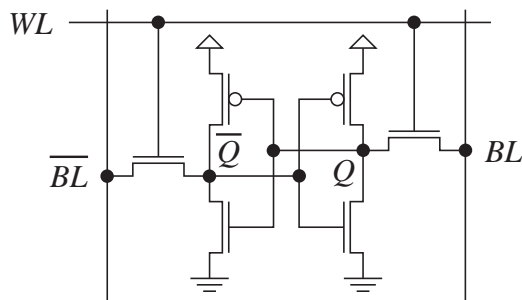
b) Capacitance  $C_x$  of node  $x$  indicated in the figure above is first precharged to  $V_{DD}$ , which is done by setting clock  $\emptyset$  low. Then the evaluation starts by setting clock  $\emptyset$  high, where a low  $A$  or low  $B$  disconnects the output from the supply, causing  $F(A, B)$  to remain at approximately  $V_{DD}$  due to the previous precharge. If instead both  $A$  and  $B$  are high, the output is discharged and becomes low.



c) For case  $F(A, B) = F(0, 1)$ , capacitance  $C_y$  of node  $y$  indicated in the figure above is discharged. If the next evaluation is  $F(A, B) = F(1, 0)$ , the voltage of node  $x$  should remain at  $V_{DD}$ , but is instead reduced due to sharing of  $C_x$ 's charge with  $C_y$ . Depending on how much the output voltage is reduced, we may need to redesign the circuit to ensure proper operation.

4.

a) Transistor schematic of a six-transistor CMOS SRAM cell



b) For example, to store  $\bar{Q} = 0, Q = 1$ ,  $WL$  is initially set to 0,  $\bar{BL}$  is set to 0, and  $BL$  is set to 1. Then  $WL$  is pulsed high long enough to allow the cross coupled inverter pair to change state hence storing the wanted content.

c) To read the cell content,  $WL$  is initially 0 while  $\bar{BL}$  and  $BL$  are precharged to 1. Then  $WL$  is pulsed high long enough for the sense amplifier to detect the voltage drop on the bit-line that is pulled towards 0 by the weak transistors in the cell. Finally the sense amplifier amplifies the voltage difference to a full swing 0 and the result is output.

d) For proper read operation, the ratio between the pull-down NMOSFET and the select NMOSFET needs to be designed high enough to prevent the memory node from changing state from 0 to 1 when the cell is connected to the precharged bit-line. For proper write operation, the ratio between the pull-up PMOSFET and the select NMOSFET must be designed low enough to allow a 0 on the bit-line change the state of the corresponding memory node.

5.

a) Resistor and capacitor values

$$R_{AC} = \frac{l_{AC}}{W_{wire}} R_{sheet} = \frac{3 \cdot 10^{-3}}{4 \cdot 10^{-6}} \cdot 0.25 \Omega \approx 190 \Omega$$

$$R_{BC} = \frac{l_{BC}}{W_{wire}} R_{sheet} = \frac{2 \cdot 10^{-3}}{4 \cdot 10^{-6}} \cdot 0.25 \Omega \approx 120 \Omega$$

$$R_{CD} = \frac{l_{CD}}{W_{wire}} R_{sheet} = \frac{4 \cdot 10^{-3}}{4 \cdot 10^{-6}} \cdot 0.25 \Omega \approx 250 \Omega$$

$$R_{CE} = \frac{l_{CE}}{W_{wire}} R_{sheet} = \frac{6 \cdot 10^{-3}}{4 \cdot 10^{-6}} \cdot 0.25 \Omega \approx 380 \Omega$$

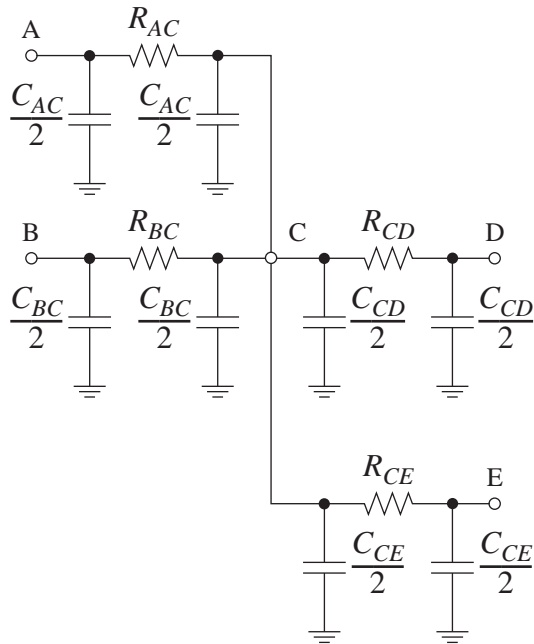
$$C_{AC} = l_{AC} W_{wire} C_{area} = 3 \cdot 10^{-3} \cdot 4 \cdot 10^{-6} \cdot 0.06 \cdot 10^{-3} \text{ F} = 720 \text{ fF}$$

$$C_{BC} = l_{BC} W_{wire} C_{area} = 2 \cdot 10^{-3} \cdot 4 \cdot 10^{-6} \cdot 0.06 \cdot 10^{-3} \text{ F} = 480 \text{ fF}$$

$$C_{CD} = l_{CD} W_{wire} C_{area} = 4 \cdot 10^{-3} \cdot 4 \cdot 10^{-6} \cdot 0.06 \cdot 10^{-3} \text{ F} = 960 \text{ fF}$$

$$C_{CE} = l_{CE} W_{wire} C_{area} = 6 \cdot 10^{-3} \cdot 4 \cdot 10^{-6} \cdot 0.06 \cdot 10^{-3} \text{ F} = 1440 \text{ fF}$$

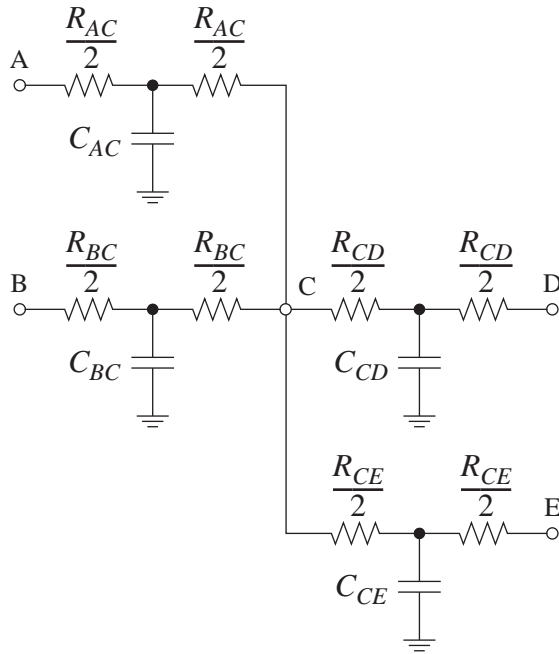
b) Interconnect model based on  $\pi$  models



Total capacitance of node C is

$$C_C = \frac{C_{AC}}{2} + \frac{C_{BC}}{2} + \frac{C_{CD}}{2} + \frac{C_{CE}}{2} = 1800 \text{ fF}$$

c) Interconnect model based on T-models



d) Elmore delay time constant based on the  $\pi$  models in b)

$$\tau_{\pi} = R_{AC} \left( \frac{C_{AC}}{2} + 2 \frac{C_{BC}}{2} + 2 \frac{C_{CD}}{2} + \frac{C_{CE}}{2} \right) + (R_{AC} + R_{CE}) \frac{C_{CE}}{2} \approx 0.88 \text{ ns}$$

Elmore delay time constant based on the T models in c)

$$\tau_{\pi} = \frac{R_{AC}}{2} C_{AC} + 2 \frac{R_{AC}}{2} (C_{BC} + C_{CD}) + \left( 2 \frac{R_{AC}}{2} + \frac{R_{CE}}{2} \right) C_{CE} \approx 0.88 \text{ ns}$$

Since  $\tau_{\pi} = \tau_T$ , there is no difference in propagation delay for these models

The propagation delay is in both cases  $t_p = 0.38\tau_{\pi} = 0.38\tau_T \approx 0.33 \text{ ns}$

6.

- a) *Logic synthesis*: Tools translate an HDL design description into a netlist.
- b) *Placement*: Precise positioning of the cells is decided.
- c) *Routing*: Interconnections are wired.
- d) *Tape out*: All information needed for mask generation is collected into a binary file and sent to the ASIC vendor.